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(71) Applicant: **INTERNATIONAL BUSINESS MACHINES CORPORATION** [US/US]; New Orchard Road, Armonk, NJ 10504 (US).

(72) Inventors: **DOKUMACI, Omer, H.**; 26A Winthrop Court, Wappinger Falls, NY 12590 (US). **DORIS, Bruce, B.**; 350 Lake Shore Drive, Brewster, NY 10509 (US).

(74) Agents: **CHAU, Frank** et al.; F. Chau & Associates, LLP, Suite 501, 1900 Hempstead Turnpike, East Meadow, NY 11554 (US).

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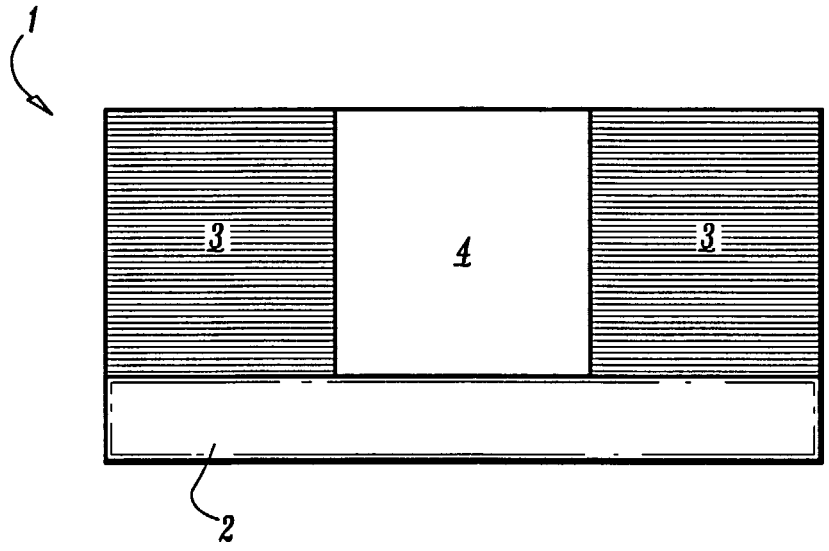
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(54) Title: STRUCTURE AND METHOD TO PRESERVE STI DURING ETCHING



(57) Abstract: Disclosed is a method of protecting a semiconductor shallow trench isolation (STI) oxide from etching, the method comprising lowering, if necessary, the upper suface of said STI oxide to a level below that of adjacent silicon active areas, depositing a nitride liner upon said STI oxide and adjacent silicon active areas in a manner effective in defining a depression above said STI oxide, filling said depression with a protective film, and removing said nitride layer from said adjacent active areas.

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